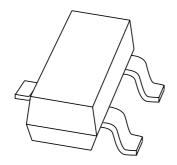
DISCRETE SEMICONDUCTORS

DATA SHEET



PMBD6100 High-speed double diode

Product specification Supersedes data of 1999 May 11 2003 Mar 25





High-speed double diode

PMBD6100

FEATURES

- Small plastic SMD package
- High switching speed: max. 4 ns
- · General application
- Continuous reverse voltage: max. 70 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 450 mA.

APPLICATIONS

 High-speed switching in surface mounted circuits.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PMBD6100	*5B

Note

1. * = p : Made in Hong Kong.* = t : Made in Malaysia.

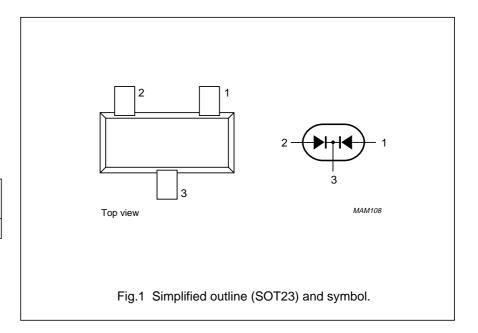
* = W : Made in China.

DESCRIPTION

The PMBD6100 consists of two high-speed switching diodes with common cathodes, fabricated in planar technology, and encapsulated in the small SOT23 plastic SMD package.

PINNING

PIN	DESCRIPTION	
1	anode (a1)	
2	anode (a2)	
3	common cathode	



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode			•	•	
V _{RRM}	repetitive peak reverse voltage		_	85	V
V _R	continuous reverse voltage		_	70	V
I _F	continuous forward current	single diode loaded; note 1; see Fig.2	_	215	mA
		double diode loaded; note 1; see Fig.2	_	125	mA

High-speed double diode

PMBD6100

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{FRM}	repetitive peak forward current		_	450	mA
I _{FSM}	non-repetitive peak forward current square wave; $T_j = 25$ °C prior to surge; see Fig.4				
		t = 1 μs	_	4	Α
		t = 1 ms	_	1	Α
		t = 1 s	_	0.5	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

Note

1. Device mounted on an FR4 printed-circuit board.

ELECTRICAL CHARACTERISTICS

 T_j = 25 $^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V _F	forward voltage	see Fig.3			
		I _F = 1 mA	550	700	mV
		I _F = 10 mA	_	855	mV
		I _F = 50 mA	_	1	V
		I _F = 100 mA	0.85	1.1	V
I _R	reverse current	see Fig.5			
		V _R = 50 V	_	100	nA
		V _R = 50 V; T _j = 150 °C	_	50	μΑ
C _d	diode capacitance	f = 1 MHz; V _R = 0; see Fig.6	_	1.5	pF
t _{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.7	_	4	ns
V _{fr}	forward recovery voltage	when switched from $I_F = 10$ mA; $t_r = 20$ ns; see Fig.8	_	1.75	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point		360	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	500	K/W

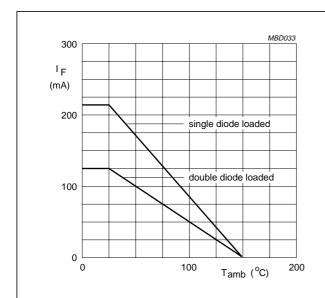
Note

1. Device mounted on an FR4 printed-circuit board.

High-speed double diode

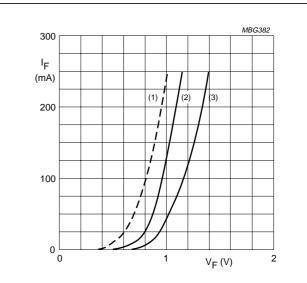
PMBD6100

GRAPHICAL DATA



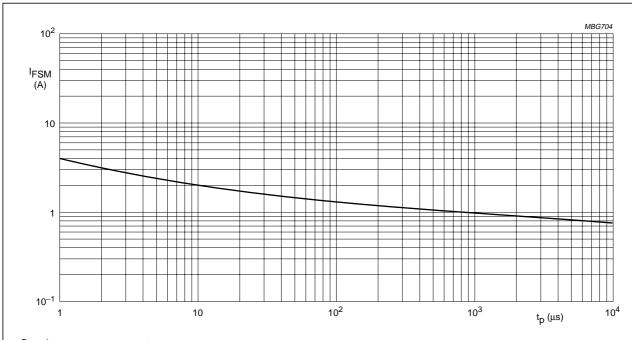
Device mounted on an FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_j = 150 \,^{\circ}\text{C}$; typical values.
- (2) $T_j = 25$ °C; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



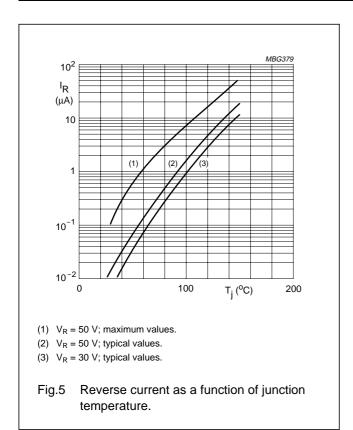
Based on square wave currents.

 T_j = 25 °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

High-speed double diode

PMBD6100



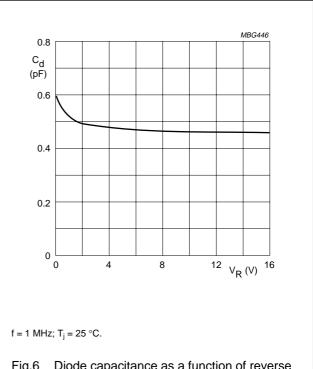
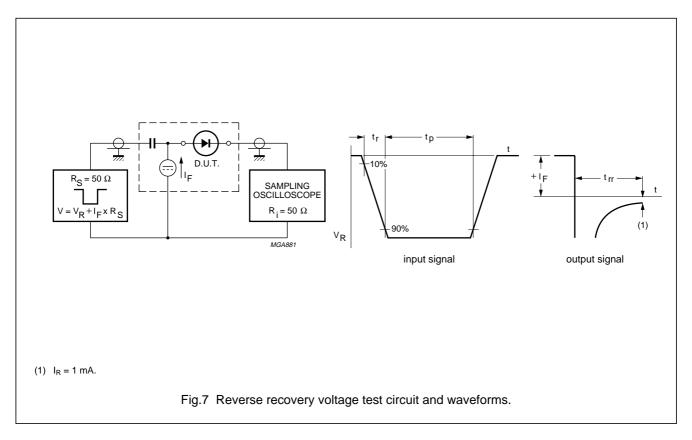
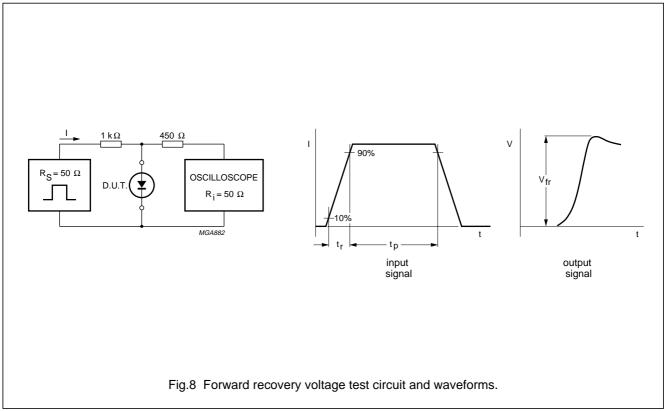


Fig.6 Diode capacitance as a function of reverse voltage; typical values.

High-speed double diode

PMBD6100





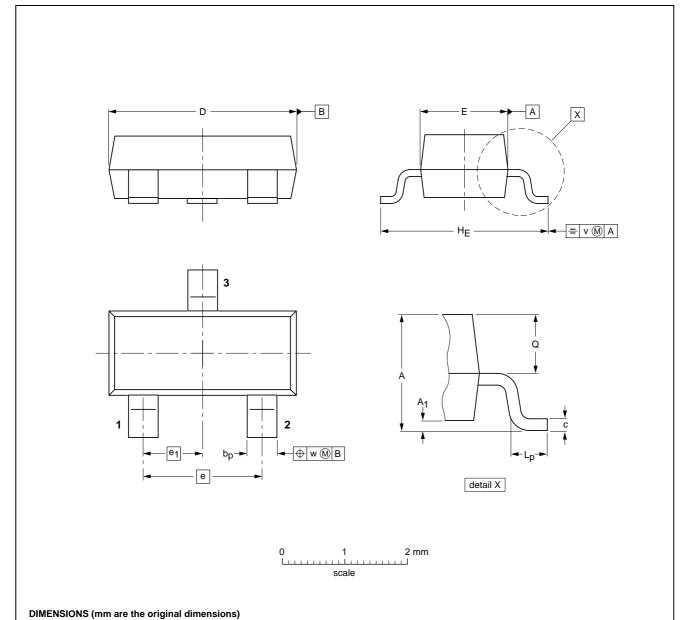
High-speed double diode

PMBD6100

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



OUTLINE		REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT23		TO-236AB				97-02-28 99-09-13	

 L_{p}

0.45

 H_{E}

Q

0.55

w

0.1

Ε

1.9

2003 Mar 25 7

 $\mathbf{A}_{\mathbf{1}}$

max.

0.48

0.15

1.1 0.9

UNIT

mm

High-speed double diode

PMBD6100

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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High-speed double diode

PMBD6100

NOTES

High-speed double diode

PMBD6100

NOTES

High-speed double diode

PMBD6100

NOTES

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